

In re the Application of: Koji NOZAKI et al. Group Art Unit: 1752

Application Number: 10/623,679 Examiner: Amanda C. Walke

Filed: July 22, 2003 Confirmation Number: 5083

For: RESIST PATTERN THICKENING MATERIAL, RESIST

PATTERN AND PROCESS FOR FORMING THE SAME, AND

SEMICONDUCTOR DEVICE AND PROCESS FOR

MANUFACTURING THE SAME

Attorney Docket Number: 030891

Customer Number: 38834

RESPONSE

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 February 22, 2008

Sir:

This paper is filed in response to the Office Action dated October 2, 2007, the response due date extended to March 2, 2008 by a two-months Extension of Time.

Remarks begin on page 2 of this paper.